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a first electrically isolated conductive trace formed at an outer region of the substrate and coupled to at least two of the plurality of bond pads.

(2) Please cancel Claim 4 without prejudice or disclaimer.

(3) Please rewrite Claim 10 as follows:

10. (Twice amended) An integrated circuit comprising:

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a substrate;

a plurality of bond pads; and

an electrically isolated conductive tester runner formed on the substrate and around the plurality of bond pads, the isolated conductive tester runner electrically coupled to at least two of the plurality of bond pads.

(4) Please cancel Claim 14 without prejudice or disclaimer.

REMARKS

Claims 1-15 were originally filed in the present Application. Claims 1-8 and 10-14 were subsequently amended, and Claims 9 and 15 were canceled without prejudice or disclaimer in response to a restriction requirement. The Applicants presently amend Claims 1 and 10 and cancel Claims 4 and 14 without prejudice or disclaimer. Accordingly, Claims 1-3, 5-8 and 10-13 are currently pending in the Application.